



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.: 10/068755 Confirmation No.: 9286  
Applicant: DENT, *et al.*  
Filed: 16/MAY/2002  
TC/A.U.: 2811  
Examiner: Im, Junghwa M  
Docket No.: DC4968 NP 1  
Customer No.: 00137  
Date: 25 January 2005  
For: Semiconductor Package and Method of Preparing Same

*Fee Sheet*

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**APPEAL BRIEF**

**Real Party in Interest**

The real party in interest in this appeal is Dow Corning Corporation, the assignee of the above application.

**Related Appeals and Interferences**

Appellants are not aware of any related appeals or interferences that will directly affect or be directly affected by or have a bearing on the Board's decision in the pending appeal.

**Status of Claims**

Claims 1-29 were originally filed in this application. Claims 15-19 and 23-25 were amended and claims 20-22 were canceled in a preliminary amendment dated 22 April 2003. Claims 30-32 were added by an amendment dated 11 August 2003. Claims 1 and 14 were amended by an

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